

SP-51 Peelable Sealant Resin

DESCRIPTION

SP-51 is an extrudable, peelable sealant resin designed to adhere to an array of substrates. The distinguishing feature of this material is its high molecular weight which makes it ideal for conventional extrusion *and* coextrusion applications. SP-51 is an ideal replacement for traditional solvent/water based coatings. With SP-51, a peelable sealant layer can be achieved in an easy, one-step process.

APPLICATIONS

- General purpose peelable sealant
- Container Lidstock

FEATURES

- Low melt index: *truly extrudable/coextrudable*
- Stable at conventional extrusion temperatures
- Good adhesion to PP, HIPS, PETG, PVdC , HDPE and PVC
- Low heat sealing temperatures
- Broad heat seal temperature range
- Easy resin transitions
- Suitable for most direct food contact applications

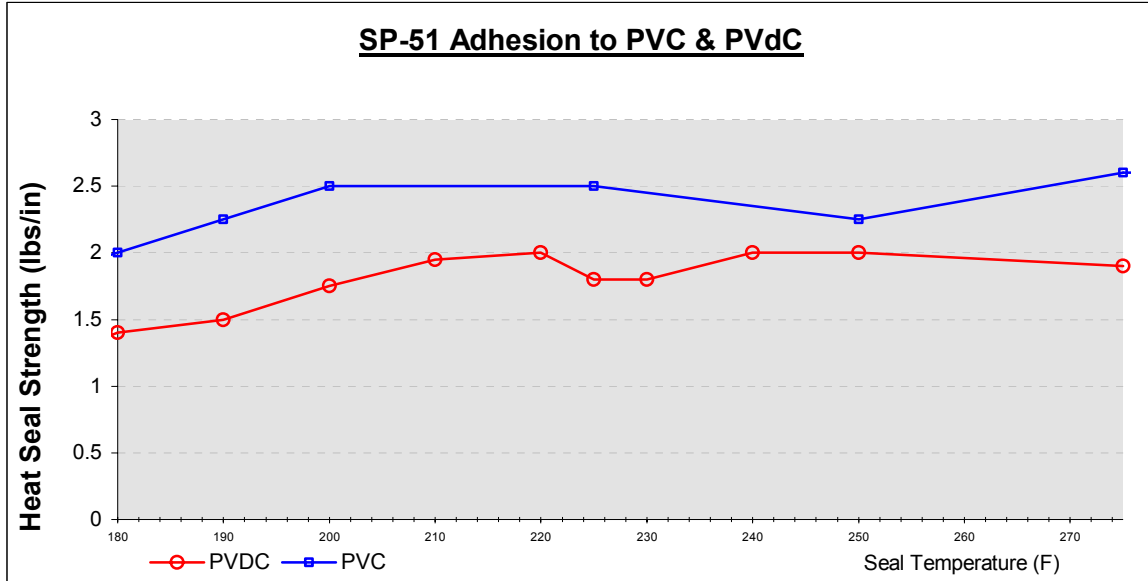
PHYSICAL PROPERTY DATA

Property	Value
Melt Index @ 190°C, 2.16 kg	5.0 dg/min
Density	0.959 g/cc
Melting Point	91°C (196°F)
Crystallization Point	74 °C (165°F)

PERFORMANCE DATA

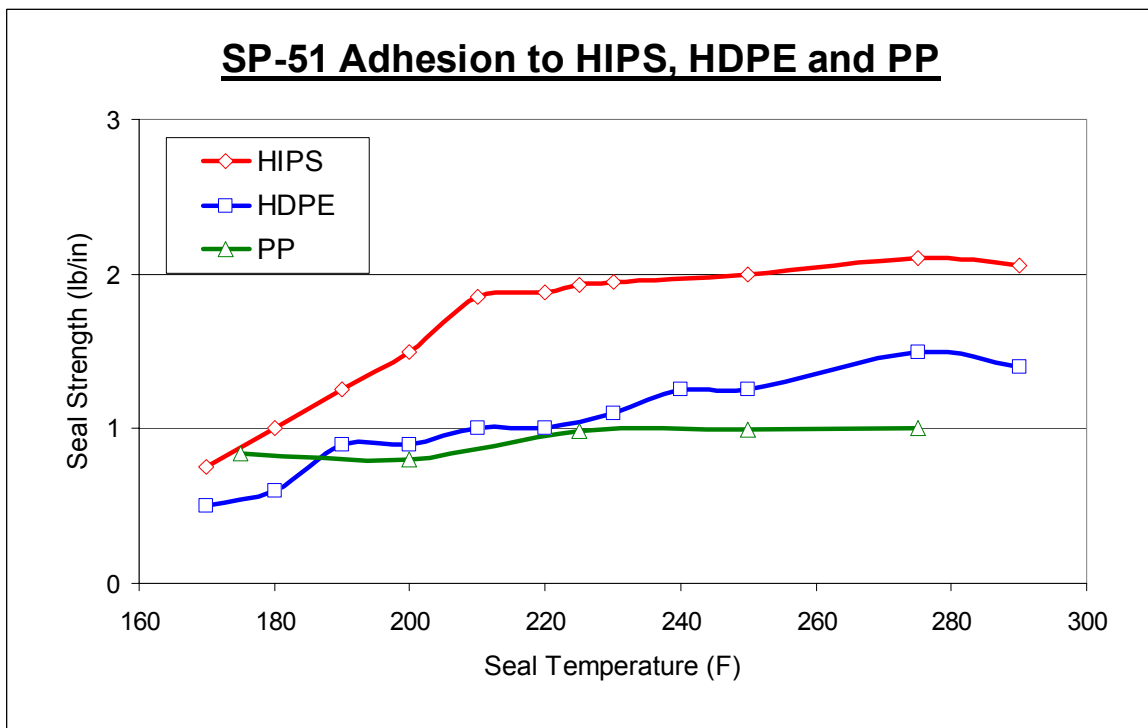
As shown in Figures 1 and 2, SP-51 exhibits a relatively flat heat seal strength versus heat seal temperature profile when heat sealed to a wide variety of substrates such as PP, HIPS, PVdC and PVC.

Fig 1



Film: PE (1.9 mil) / SP-50 (0.6 mil) Heat Seal Conditions: 40 psi, 1 sec, 10 in/min, aged 1 day

Fig 2



FDA STATUS

MSI Technology

SYSTEM POLYMERS

SP-51 is acceptable for use in most direct food contact applications. Contact your MSIT representative for more information.

PROCESSING INFORMATION

SP-51 can be processed on conventional blown film and cast film extrusion equipment. The recommended melt temperature range for SP-51 is 365 to 450°F. A typical extruder temperature profile is shown below.

Temperature	Zone 1	Zone 2	Zone 3	Adapter	Die
°F	230	330	400	420	420
°C	105	165	200	215	215

PACKAGING

SP-51 is available in 55-lb bags or 1000-lb boxes.